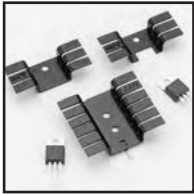


# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



## 270/272/280 SERIES

### Small Footprint Low-Cost Heat Sinks

TO-220, TO-202

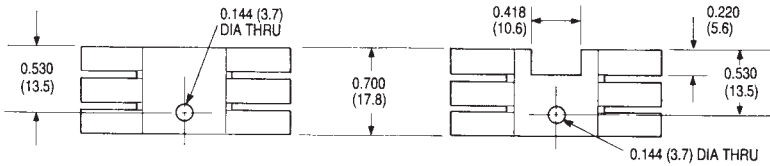
Standard P/N	Height Above PC Board in. (mm)	Horizontal Mounting Maximum Footing in. (mm)	Solderable Tab Options	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
270-AB	0.375 (9.4)	1.750 (44.5) x 0.700 (17.8)	—	70°C @ 4W	6.0°C/W @ 400 LFM	0.0052 (2.36)
272-AB	0.375 (9.4)	1.750 (44.5) x 1.450 (36.8)	01,02	42°C @ 4W	3.6°C/W @ 400 LFM	0.0105 (5.72)
280-AB	0.375 (9.4)	1.750 (44.5) x 0.700 (17.8)	—	70°C @ 4W	6.0°C/W @ 400 LFM	0.0048 (2.18)

Material: Aluminum, Black Anodized

These exceptionally low-cost heat sinks can be mounted horizontally under a TO-220 or TO-202 case style with a maximum height of only 0.375 in. (9.4). For added performance, a 271 Series heat sink can also be used for double-sided heat dissipation.

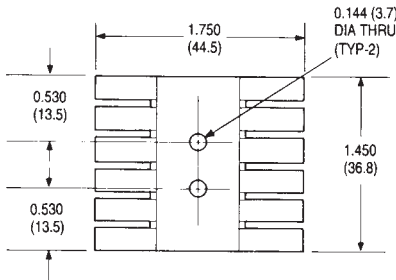
The 270-AB and 280-AB accept one power semiconductor; the 272-AB is designed for two power semiconductors. Specify solderable tab options for the 272 Series by the addition of suffix "01" or "02" to the standard part number (i.e. 272-AB01 or 272-AB02).

### MECHANICAL DIMENSIONS

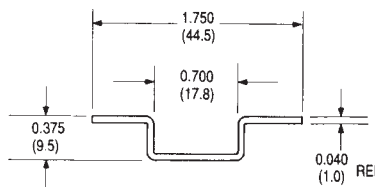


270 SERIES

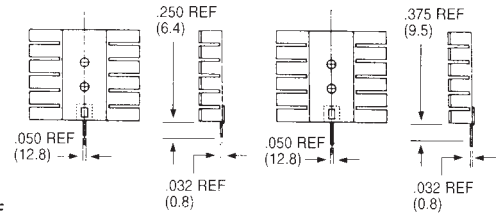
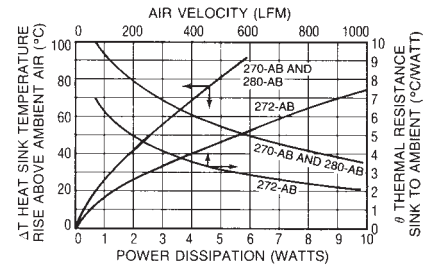
280 SERIES



272 SERIES



### NATURAL AND FORCED CONVECTION CHARACTERISTICS



272AB01

272AB02

Dimensions: in. (mm)

#### Note:

1. Suggested Tab Hole = 0.075 ±0.003 plated with 0.100 pad